



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-10-05
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Floriana San Biagio	<b>Representative Title</b>	AMG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CKN5*VA06AAJ	A	SH1A	2016-10-05
Amount	UoM	Unit type	ST ECOPACK Grade	
3.39	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
Not Applicable	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Tin/Silver/Copper (SAC125)	Tin/Silver/Copper (Sn/Ag/Cu)	N/A		



Package Designator	Size	Nbr of instances	Shape	
BGA	1.4x1.5x0.35	12	bulk solder	
Comment	Package: N5 CSPS0.4 BP 5-16; MDF valid for STC3117JT			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	CKN5*VA06AAJ					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	3.389	mg	supplier	die	Silicon (Si)	7440-21-3		1.937	mg	571538	571555
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	1475	1475
				supplier	metallization	Copper (Cu)	7440-50-8		0.019	mg	5606	5606
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.005	mg	1475	1475
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	590	590
				supplier	Passivation	Silicon Nitride	12033-89-5		0.006	mg	1770	1770
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	5606	5606
				supplier	polymer die coating	silica vitreous	60676-86-0		0.382	mg	112773	112777
				supplier	polymer die coating	Epoxy resin	Proprietary		0.138	mg	40719	40720
				supplier	polymer die coating	Acrylic polymer	Proprietary		0.138	mg	40719	40720
				supplier	polymer die coating	Bis-phenol A diglycidyl ether	25036-25-3		0.047	mg	13957	13957
				supplier	polymer die coating	carbon black	1333-86-4		0.004	mg	1151	1151
				supplier	polymer die coating	chlorine residue	7782-50-5		0.000	mg	59	59
				supplier	polymer die coating	Iron compound	7439-89-6		0.039	mg	11626	11626
				supplier	polymer die coating	Zinc compound	7440-66-6		0.039	mg	11626	11626
				supplier	bump	Tin (Sn)	7440-31-5		0.597	mg	176153	176158
				supplier	bump	Silver (Ag)	7440-22-4		0.007	mg	2154	2154
				supplier	bump	Copper (Cu)	7440-50-8		0.003	mg	885	885
				supplier	bump	Nickel (Ni)	7440-02-0		0.0003	mg	89	89
				JIG - R	bump	Lead (Pb)	7439-92-1		0.0001	mg	30	30